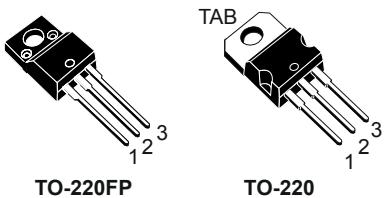


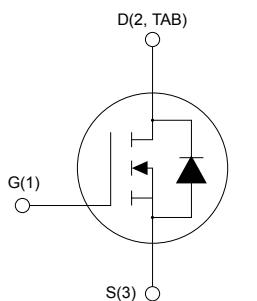
N-channel 650 V, 390 mΩ typ., 8.5 A MDmesh M5 Power MOSFET in a TO-220FP and TO-220 packages

Features



Order code	$V_{DS} @ T_J \text{ max.}$	$R_{DS(on)} \text{ max.}$	I_D
STF12N65M5	710 V	430 mΩ	
STP12N65M5			8.5 A

- Extremely low $R_{DS(on)}$
- Low gate charge and input capacitance
- Excellent switching performance
- 100% avalanche tested



AM01475v1_noZen

Applications

- Switching applications

Description

This device is an N-channel Power MOSFET based on the MDmesh M5 innovative vertical process technology combined with the well-known PowerMESH horizontal layout. The resulting product offers extremely low on-resistance, making it particularly suitable for applications requiring high power and superior efficiency.



Product status links

[STF12N65M5](#)[STP12N65M5](#)

Product summary

Order code	STF12N65M5
Marking	12N65M5
Package	TO-220FP
Packing	Tube
Order code	STP12N65M5
Marking	12N65M5
Package	TO-220
Packing	Tube

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		TO-220FP	TO-220	
V _{DS}	Drain-source voltage	650		V
V _{GS}	Gate-source voltage	25		V
I _D	Drain current (continuous) at T _C = 25 °C	8.5 ⁽¹⁾	8.5	A
	Drain current (continuous) at T _C = 100 °C	5.4 ⁽¹⁾	5.4	
I _{DM} ⁽²⁾	Drain current (pulsed)	34	34	A
P _{TOT}	Total power dissipation at T _C = 25 °C	25	70	W
I _{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by T _J max.)	2.5		A
E _{AS}	Single pulse avalanche energy (starting T _J = 25 °C, I _D = I _{AR} , V _{DD} = 50 V)	150		mJ
dv/dt ⁽³⁾	Peak diode recovery voltage slope	15		V/ns
V _{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s, T _C = 25 °C)	2.5		kV
T _{stg}	Storage temperature range	-55 to 150		°C
T _J	Operating junction temperature range			°C

1. Limited by maximum junction temperature.
2. Pulse width is limited by safe operating area.
3. I_{SD} ≤ 8.5 A, di/dt ≤ 400 A/μs, V_{DS} (peak) < V_{(BR)DSS}, V_{DD} = 400 V.

Table 2. Thermal data

Symbol	Parameter	Value		Unit
		TO-220FP	TO-220	
R _{thJC}	Thermal resistance, junction-to-case	5.00	1.79	°C/W
R _{thJA}	Thermal resistance, junction-to-ambient	62.5		°C/W

2 Electrical characteristics

$T_C = 25^\circ\text{C}$ unless otherwise specified.

Table 3. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	650			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 650 \text{ V}$		1		μA
		$V_{GS} = 0 \text{ V}, V_{DS} = 650 \text{ V}, T_C = 125^\circ\text{C}$ ⁽¹⁾			100	
I_{GSS}	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			100	nA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	3	4	5	V
$R_{\text{DS(on)}}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 4.3 \text{ A}$		390	430	$\text{m}\Omega$

1. Specified by design, not tested in production.

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$	-	900	-	pF
C_{oss}	Output capacitance		-	22	-	pF
C_{rss}	Reverse transfer capacitance		-	2	-	pF
$C_{o(tr)}^{(1)}$	Equivalent capacitance time related	$V_{DS} = 0 \text{ to } 520 \text{ V}, V_{GS} = 0 \text{ V}$	-	64	-	pF
$C_{o(er)}^{(2)}$	Equivalent capacitance energy related		-	21	-	pF
R_g	Intrinsic gate resistance	$f = 1 \text{ MHz}, I_D = 0 \text{ A}$	-	5	-	Ω
Q_g	Total gate charge	(see Figure 17. Test circuit for gate charge behavior)	-	20	-	nC
Q_{gs}	Gate-source charge		-	4.8	-	nC
Q_{gd}	Gate-drain charge		-	8.3	-	nC

- $C_{o(tr)}$ is an equivalent capacitance that provides the same charging time as C_{oss} while V_{DS} is rising from 0 V to the stated value.
- $C_{o(er)}$ is an equivalent capacitance that provides the same stored energy as C_{oss} while V_{DS} is rising from 0 V to the stated value.

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(v)}$	Voltage delay time	$V_{DD} = 400 \text{ V}, I_D = 5 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$	-	22.6	-	ns
$t_{r(v)}$	Voltage rise time		-	17.6	-	ns
$t_{f(i)}$	Current fall time	(see Figure 18. Test circuit for inductive load switching and diode recovery times and Figure 21. Switching time waveform)	-	15.6	-	ns
$t_{c(off)}$	Crossing time		-	23.4	-	ns

Table 6. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		8.5	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		34	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 8.5 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.5	V
t_{rr}	Reverse recovery time	$I_{SD} = 8.5 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s},$ $V_{DD} = 100 \text{ V}$	-	230		ns
Q_{rr}	Reverse recovery charge	(see Figure 18. Test circuit for inductive load switching and diode recovery times)	-	2.2		μC
I_{RRM}	Reverse recovery current		-	19		A
t_{rr}	Reverse recovery time	$I_{SD} = 8.5 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s},$ $V_{DD} = 100 \text{ V}, T_J = 150 \text{ }^\circ\text{C}$	-	280		ns
Q_{rr}	Reverse recovery charge	(see Figure 18. Test circuit for inductive load switching and diode recovery times)	-	2.7		μC
I_{RRM}	Reverse recovery current		-	19		A

1. Pulse width is limited by safe operating area.
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%.

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area for TO-220FP

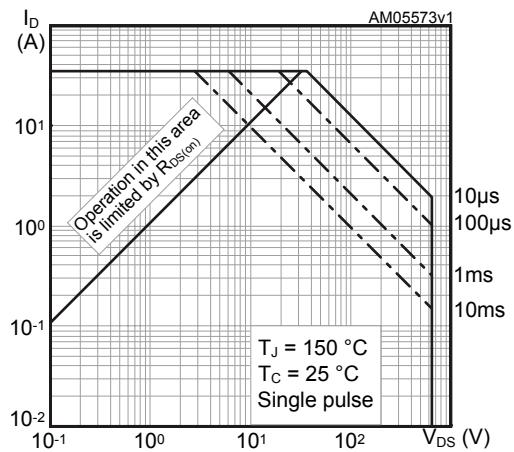


Figure 2. Normalized transient thermal impedance for TO-220FP

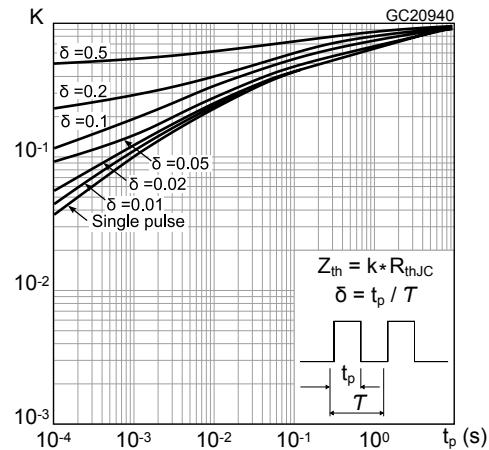


Figure 3. Safe operating area for TO-220

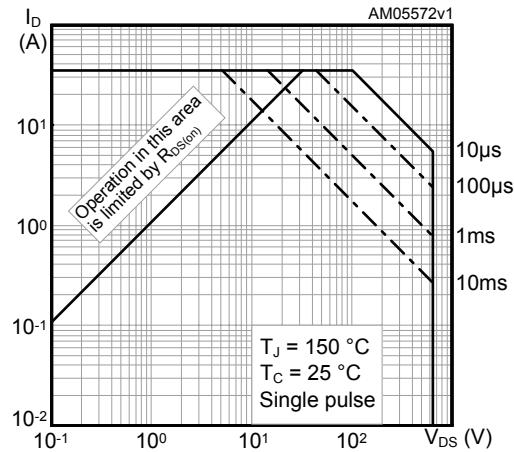


Figure 4. Normalized transient thermal impedance for TO-220

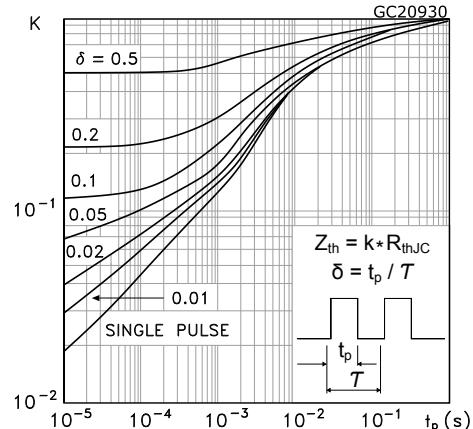


Figure 5. Typical output characteristics

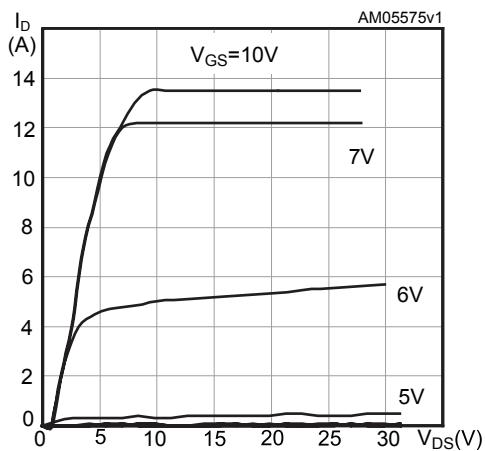


Figure 6. Typical transfer characteristics

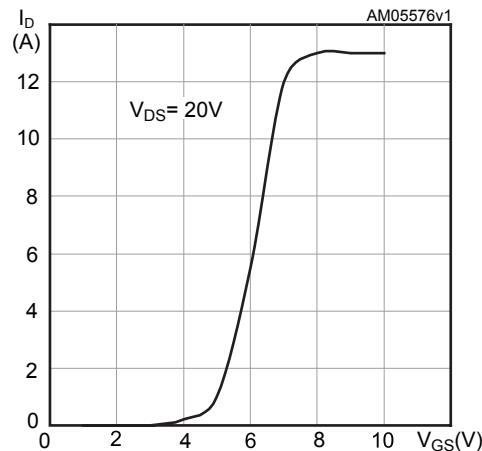


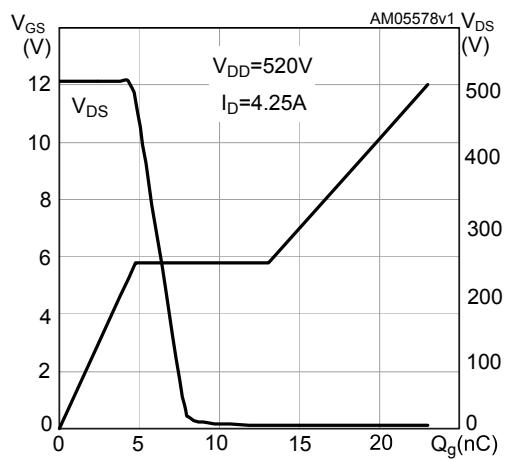
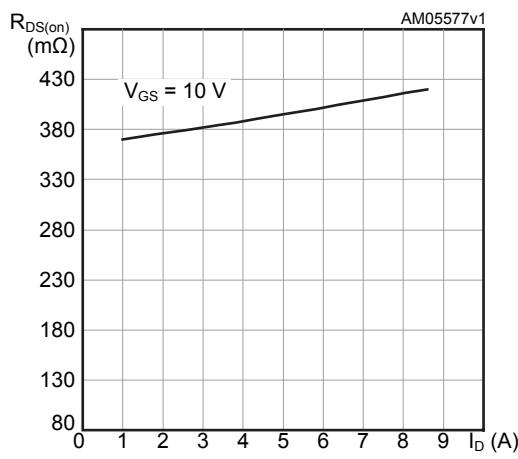
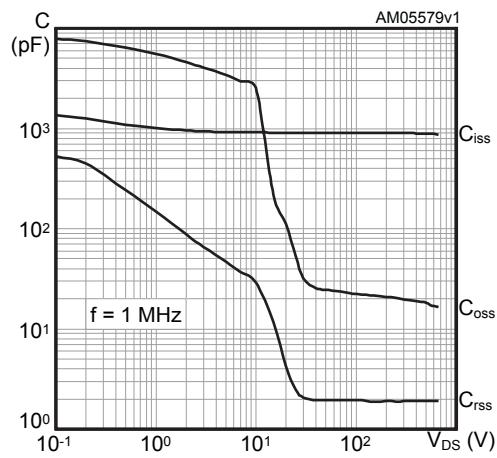
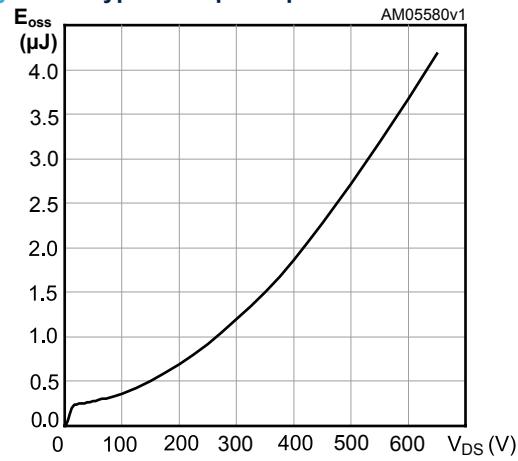
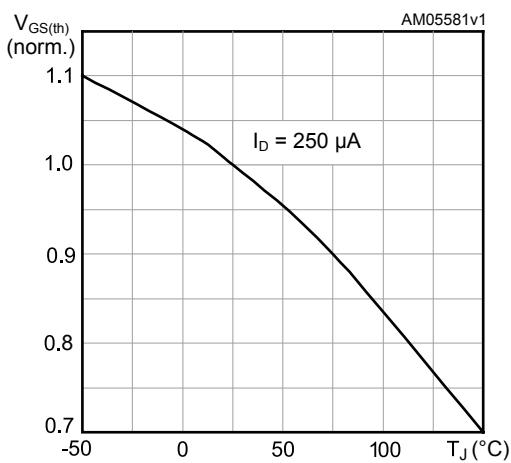
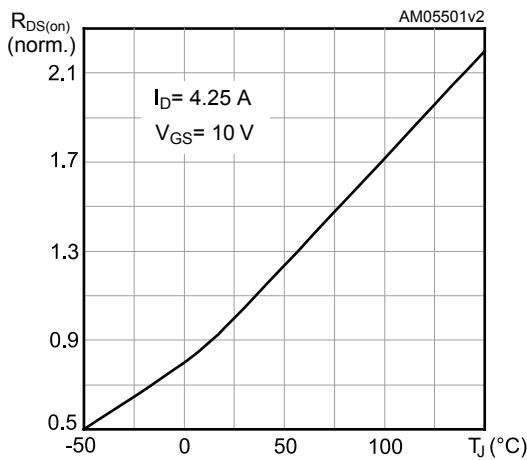
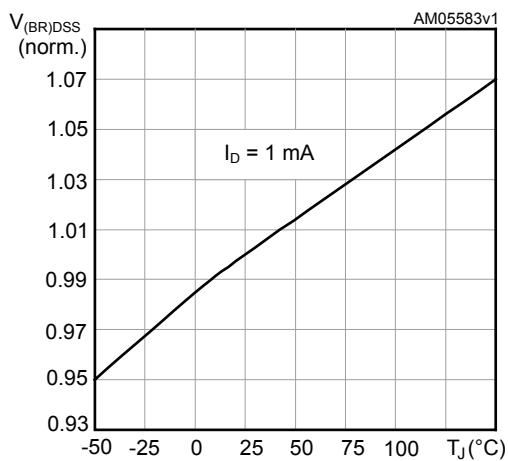
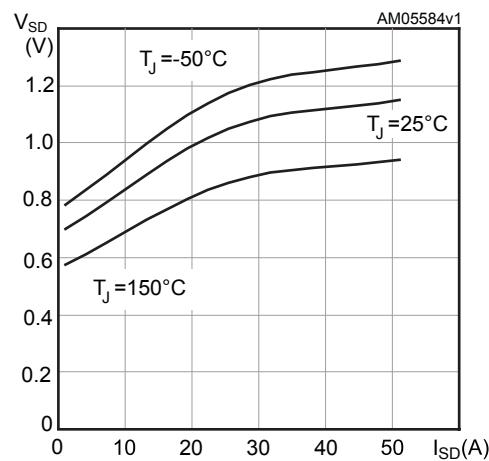
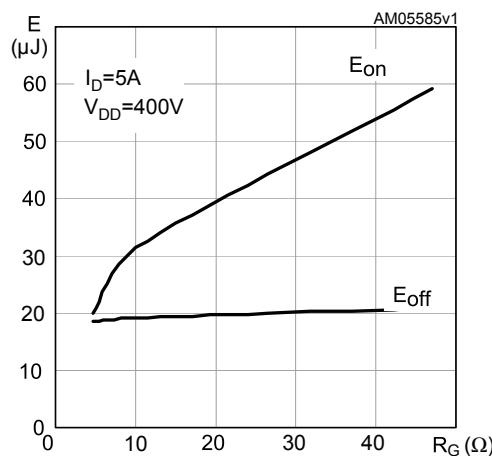
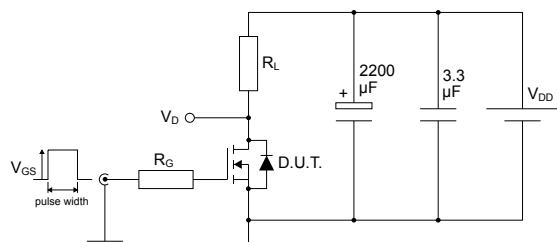
Figure 7. Typical gate charge characteristics

Figure 8. Typical drain-source on-resistance

Figure 9. Typical capacitance characteristics

Figure 10. Typical output capacitance stored energy

Figure 11. Normalized gate threshold voltage vs temperature

Figure 12. Normalized on-resistance vs temperature


Figure 13. Normalized breakdown voltage vs temperature**Figure 14. Typical reverse diode forward characteristics****Figure 15. Typical switching energy vs gate resistance**

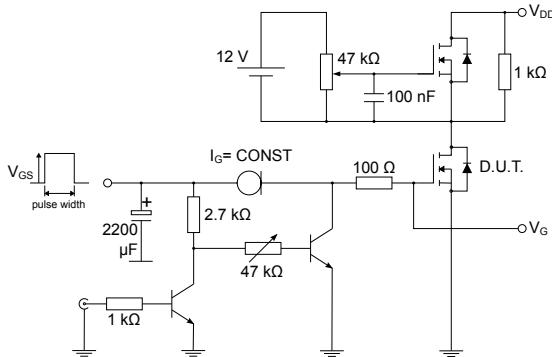
3 Test circuits

Figure 16. Test circuit for resistive load switching times



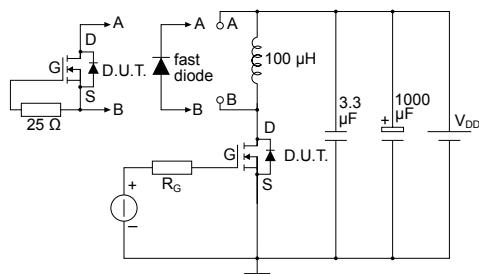
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Figure 17. Test circuit for gate charge behavior



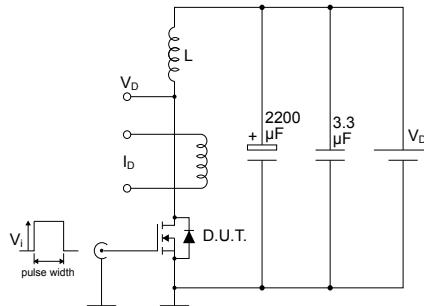
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Figure 18. Test circuit for inductive load switching and diode recovery times



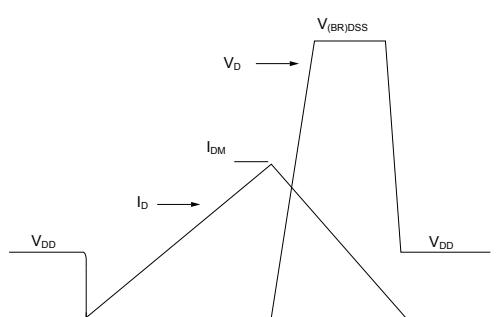
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Figure 19. Unclamped inductive load test circuit



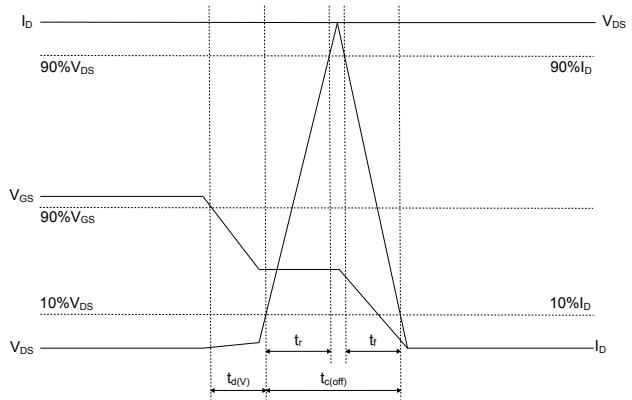
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Figure 20. Unclamped inductive waveform



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Figure 21. Switching time waveform



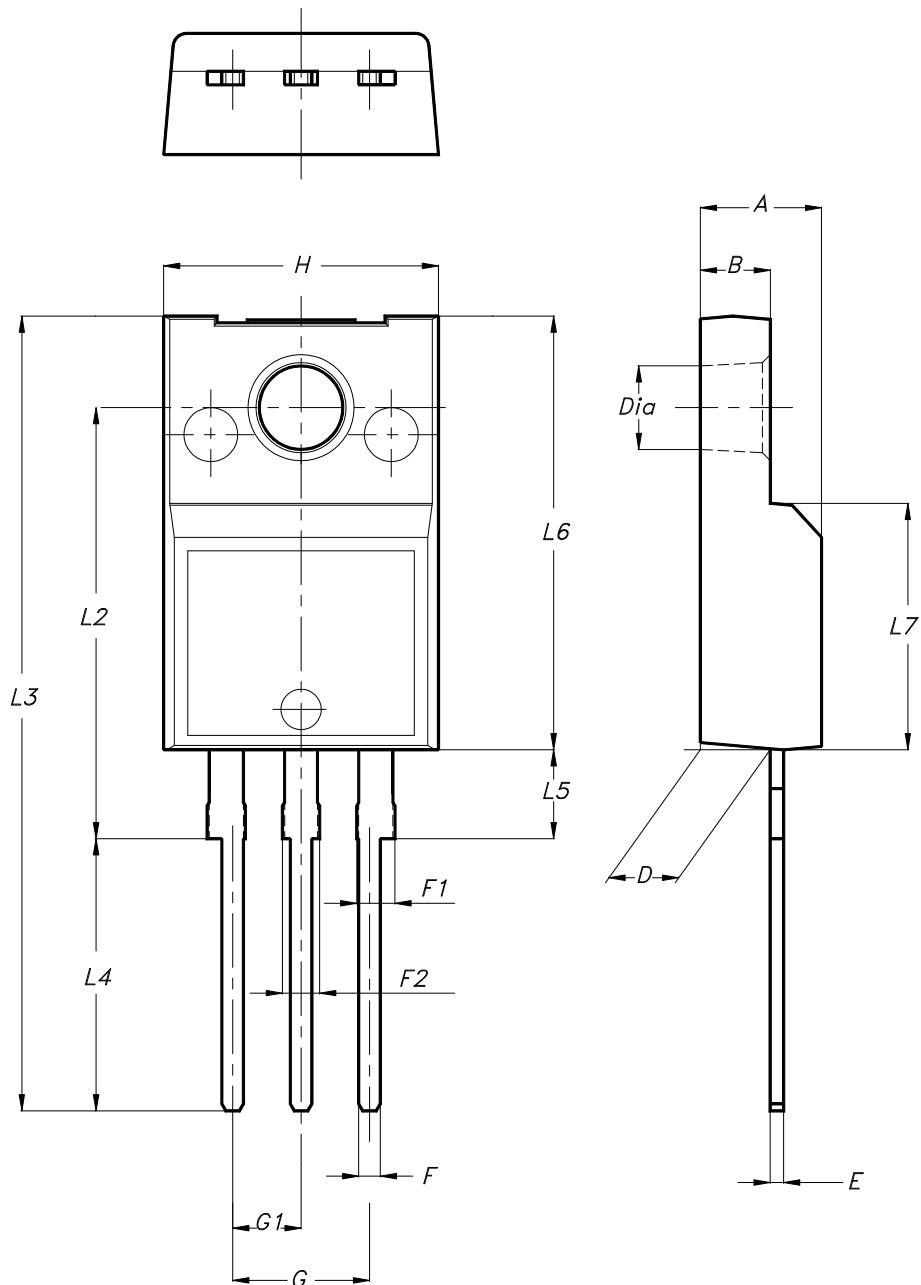
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4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 TO-220FP package information

Figure 22. TO-220FP package outline



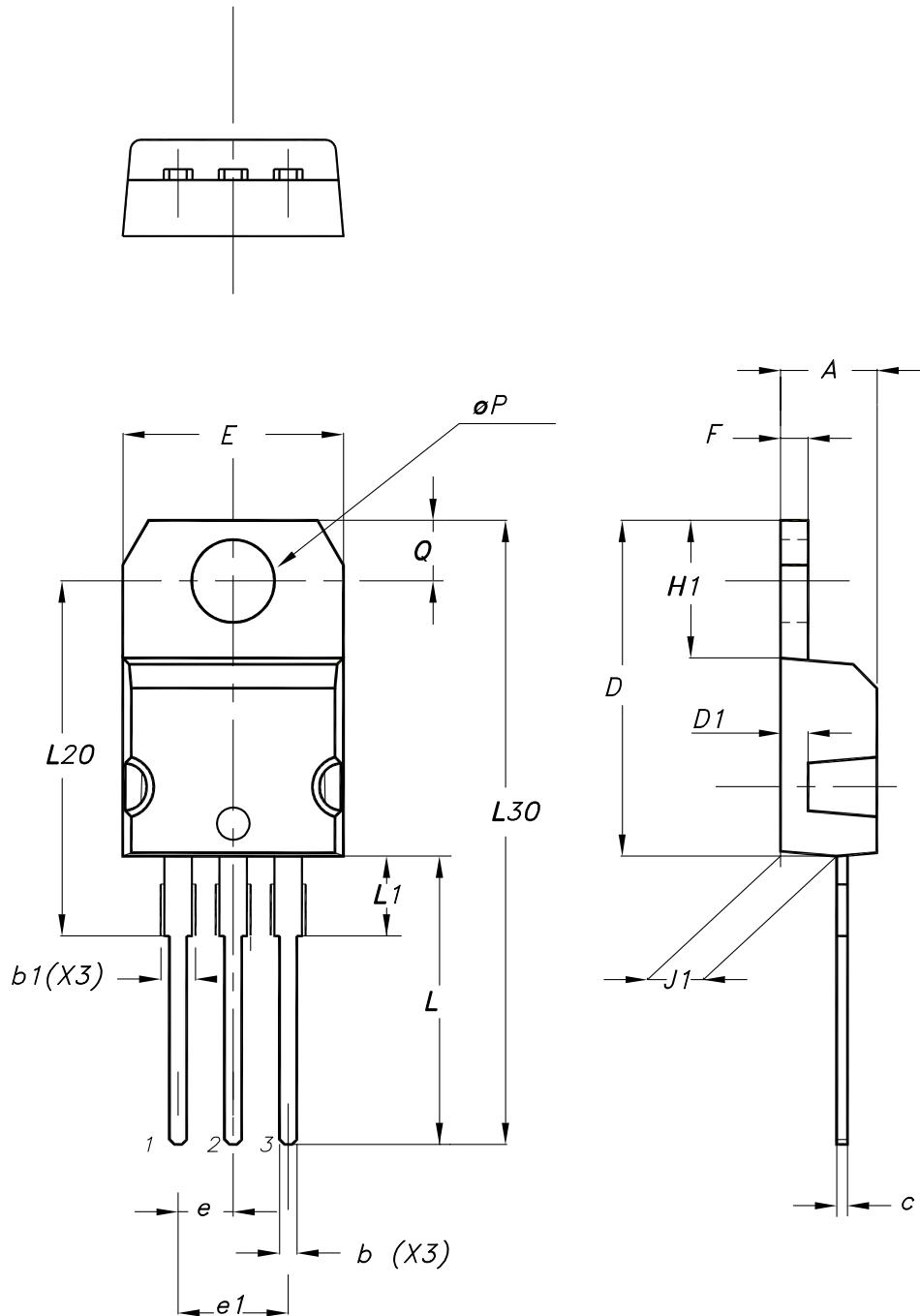
7012510_Rev_13_B

Table 7. TO-220FP package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
B	2.50		2.70
D	2.50		2.75
E	0.45		0.70
F	0.75		1.00
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.20
G1	2.40		2.70
H	10.00		10.40
L2		16.00	
L3	28.60		30.60
L4	9.80		10.60
L5	2.90		3.60
L6	15.90		16.40
L7	9.00		9.30
Dia	3.00		3.20

4.2 TO-220 type A package information

Figure 23. TO-220 type A package outline



0015988_typeA_Rev_23

Table 8. TO-220 type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95
Slug flatness		0.03	0.10

Revision history

Table 9. Document revision history

Date	Version	Changes
24-Feb-2009	1	First release.
27-Feb-2009	2	Corrected package information on first page.
21-Jan-2010	3	Document status promoted from preliminary data to datasheet.
29-Jun-2010	4	<ul style="list-style-type: none">– <i>Figure 15: Normalized on resistance vs temperature</i> has been updated.– V_{GS} value in <i>Table 4</i> has been corrected.
22-Jun-2011	5	<ul style="list-style-type: none">Updated <i>Figure 18</i> and <i>Figure 20</i>.Updated gate charge in <i>Table 5</i> and switching time in <i>Table 6</i>.
11-Mar-2022	6	<ul style="list-style-type: none">The part numbers STD12N65M5, STI12N65M5 and STU12N65M5 have been removed and the document has been updated accordingly.Updated title, Features and Description on cover page.Modified R_g value in the Table 4. Dynamic.Updated Section 4 Package information.Minor text changes.

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